



Rev	R1	C10	C9	Fco
A	53k6	100nF	100pF	1kHz
A1	150k	33nF	33pF	2.4kHz
B	309k	15nF	10pF	5.0kHz

**board connection for inverting BB:**

1 = negative output  
 2 = positive input  
 3 = ground

Jack #1  
 1 | 2 | 3

Revision History	
Revision	Notes
A	* First release: RHPZ 17kHz, Fco 1kHz
A1	* Fco 2.4kHz
B	* Fco 5.0kHz

**NOTES:**

- 1) built on PCB PMP2763 RevA
- 2) inverting BuckBoost, refer to board connection
- 3) R8 for test purposes only
- 4) TP1/TP13/TP16 to connect Network Analyzer
- 5) designed for pulsed load 10mA / 140mA
- 6) for max. effcy L2 could be DR125-221-R (size 12.5mm x 12.5mm x 6mm)

**ASSEMBLY:**

- 1) R7 SHORT
- 2) C8, C11 open
- 3) R4, R6, R9 open
- 4) L1, D1 open
- 5) TP5, TP7, TP8, TP11, TP15 open
- 6) C2, C3, C5 will not meet pattern
- 7) D2 - SMA on SMB pattern
- 8) pattern L2 matches up to DR127 series

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Number: PMP10210 Rev: B  
 SVN Rev: Not in version control  
 Drawn By:  
 Engineer: B.Geck

Designed for: Public Release Mod. Date: 7/17/2015  
 Project Title: inv. BuckBoost w/ TPS54060A  
 Sheet Title:  
 Assembly Variant: Variant name not interpreted Sheet: 1 of 1  
 File: PMP10210RevB.SchDoc Size: A4  
 Contact: <http://www.ti.com/support>



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